

BENHA UNIVERSITY FACULTY OF ENGINEERING (SHOUBRA) ELECTRONICS AND COMMUNICATIONS ENGINEERING



CCE 201 Solid State Electronic Devices (2022 - 2023) term 231

Lecture 5: PN junction.

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Outlines

PN Junction with Open-Circuit Terminals.

The pn Junction with an Applied Voltage.

Summary.

The PN Junction with Open-Circuit Terminals

- > PN junction structure:
 - p-type semiconductor
 - n-type semiconductor
 - metal contact for connection
- Q: What is state of pn junction with open-circuit terminals?
 - p-type material contains majority of holes
 These holes are neutralized by equal amount of bound negative charge.
 - n-type material contains majority of free electrons
 These electrons are neutralized by equal amount of bound positive charge.
- Bound charge
 - Charge of opposite polarity to free electrons / holes of a given material.
 - Neutralizes the electrical charge of these majority carriers.
 - Does not affect concentration gradients (current).





- What happens when a pn-junction is newly formed, when the p-type and n-type semiconductors first touch one another?
 - □ Step #1: The p-type and n-type semiconductors are joined at the junction.



Step #2: Diffusion begins. Those free electrons and holes which are closest to the junction will recombine and, essentially, eliminate one another.

p-type

n-type

□ Step #3: The depletion region begins to form – as diffusion occurs and free electrons recombine with holes.



□ Step #4: The "uncovered" bound charges affect a voltage differential across the depletion region. The magnitude of this barrier voltage (V0) differential grows, as diffusion continues.



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□ Step #5: The barrier voltage (V_0) is an electric field whose polarity opposes the direction of diffusion current (I_D) . As the magnitude of V_0 increases, the magnitude of I_D decreases.



□ Step #6: Equilibrium is reached, and diffusion ceases, once the magnitudes of diffusion and drift currents equal one another – resulting in no net flow.

- □ In addition to majority-carrier diffusion current (I_D), a component of current due to minority carrier drift exists (I_S).
- □ Specifically, some of the thermally generated in the p-type and n-type materials move toward and reach the edge of the depletion region.
- Therefore, they experience the electric field (V₀) in the depletion region and are swept across it.
- Unlike diffusion current, the polarity of V₀ reinforces this drift current.

Once equilibrium is achieved, no net current flow exists $(I_{net} = I_D - I_S)$ within the *pn*-junction while under open-circuit condition.

(+)

(+)

(+)

(+)

n-type

depletion

region

Θ

 \bigcirc

Θ

 \bigcirc

p-type

- \triangleright PN-junction built-in voltage (V₀) is the equilibrium value of barrier voltage.
 - Generally, it takes on a value between 0.6 and 0.9V for silicon at room temperature.
 - This voltage is applied across depletion region, not terminals of pn junction.

 \Box Power cannot be drawn from V₀.

 $V_0 =$ barrier voltage $V_T =$ thermal voltage $N_A =$ acceptor doping concentration $N_D =$ donor doping concentration $n_i =$ concentration of free electrons... ...in intrinsic semiconductor

$$V_0 = V_T \ln \left(\frac{N_A N_D}{n_i^2} \right)$$

Report 1

- Prove that the pn junction built -in voltage is given by: $V_0 = V_T \ln\left(\frac{N_A N_D}{n_1^2}\right)$
- Hint: it can be derived from the equality of drift current and diffusion current at equibrium.
- electron drift current = electron diffusion current.

- How is the charge stored in both sides of the depletion region defined?
- > What information can be derived from this equality?
 - □ In reality, the depletion region exists almost entirely on one side of the pn junction – due to great disparity between NA > ND.

$$qAx_{p}N_{A} = qAx_{n}N_{D} \rightarrow \frac{X_{n}}{X_{p}} = \frac{N_{A}}{N_{D}}$$

□ Note that both x_p and x_n may be defined in terms of the depletion region width (W).

$$W = x_n + x_p = \sqrt{\frac{2\varepsilon_s}{q} \left(\frac{1}{N_A} + \frac{1}{N_D}\right) V_0}$$

$$x_{n} = W \frac{N_{A}}{N_{A} + N_{D}}$$
$$x_{p} = W \frac{N_{D}}{N_{A} + N_{D}}$$



 $|Q_+| =$ magnitude of charghe on *n*-side of junction q = magnitude of electric charge A = cross-sectional area of junction $x_n =$ penetration of depletion region into *n*-side $N_D =$ concentration of donor atoms

$$|Q_{+}| = qAx_{n}N_{D}$$

$$|Q_{\perp}| = qAx_{p}N_{A}$$

 $|Q_{-}|$ = magnitude of charghe on *n*-side of junction q = magnitude of electric charge A = cross-sectional area of junction x_{p} = penetration of depletion region into *p*-side N_{A} = concentration of acceptor atoms

$$Q_{j} = |Q_{\pm}| = Aq \left(\frac{N_{A}N_{D}}{N_{A} + N_{D}} \right) W$$
$$Q_{j} = A \sqrt{2\varepsilon_{S}q \left(\frac{N_{A}N_{D}}{N_{A} + N_{D}} \right) V_{0}}$$

Summary :

- What has been learned about the pn-junction?
 - Composition: The pn junction is composed of two silicon-based semiconductors, one doped to be p-type and the other n-type.
 - **majority carriers**: Are generated by doping. Holes are present on p-side, free electrons are present on n-side.
 - Bound charges: charge of majority carriers are neutralized electrically by bound charges.
 - □ Diffusion current ID: those majority carriers close to the junction will diffuse across, resulting in their elimination.
 - Depletion region: As these carriers disappear, they release bound charges and effect a voltage differential V0.
 - Depletion-layer voltage: As diffusion continues, the depletion layer voltage (V0) grows, making diffusion more difficult and eventually bringing it to halt.
 - □ Minority carriers: Are generated thermally. Free electrons are present on p-side, holes are present on n-side.
 - Drift current IS: The depletion-layer voltage (V0) facilitates the flow of minority carriers to opposite side.
 - □ Open circuit equilibrium ID = IS

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Summary.

> pn-junction under three conditions:

- (a) open-circuit where a barrier voltage V_0 exists.
- **(b)** reverse bias where a dc voltage V_R is applied.

(c) forward bias – where a dc voltage V_F is applied.







reverse bias case

- the externally applied voltage V_R adds to the barrier voltage V₀
 - > ...increase effective barrier
- this reduces rate of diffusion, reducing I_D
 - > if $V_R > 1 V$, I_D will fall to 0A
- the drift current *I_S* is unaffected, but dependent on temperature
- result is that *pn* junction will conduct **small** drift current *I_S*

minimal current flows in reversebias case

forward bias case

- the externally applied voltage V_F
 subtracts from the barrier voltage V₀
 - …decrease effective barrier
- this increases rate of diffusion, increasing I_D
- the drift current *I_S* is unaffected, but dependent on temperature
- result is that *pn* junction will conduct
 significant current *I_D I_S*

significant current flows in forward-bias case

Forward-Bias Case

Observe that decreased barrier voltage will be accompanied by...

(1) decrease in stored uncovered charge on both sides of junction

(2) smaller depletion region

□ Width of depletion can given as:

 ε_{s} = electrical permiability of silicon (11.7 ε_{0} = 1.04E – 12F / cm)

$$\mathcal{N} = x_n + x_p = \sqrt{\frac{2\varepsilon_s}{q} \left(\frac{1}{N_A} + \frac{1}{N_D}\right) \left(\frac{V_0 - V_F}{\text{action:}}\right)}{\sqrt{\frac{1}{N_A - V_F}}}$$

$$Q_j = A \sqrt{2\varepsilon_s q \left(\frac{N_A N_D}{N_A + N_D}\right) \left(\frac{V_0 - V_F}{\text{outh } V_0 - V_F}\right)}{\sqrt{\frac{1}{N_A - N_D}}}$$

$$Q_j = \text{magnitude of charge stored on either side of depletion region}}$$

Reverse-Bias Case

Observe that increased barrier voltage will be accompanied by...

(1) increase in stored uncovered charge on both sides of junction

(2) Wider depletion region

□ Width of depletion can given as:

 ε_{s} = electrical permiability of silicon (11.7 ε_{0} = 1.04E – 12F / cm)

$$\mathcal{N} = x_n + x_p = \sqrt{\frac{2\varepsilon_s}{q} \left(\frac{1}{N_A} + \frac{1}{N_D}\right) \left(\frac{V_0 + V_R}{action}\right)}_{\substack{\text{action:} \\ \text{replace } V_0 \\ \text{with } V_0 + V_R}}$$
$$Q_j = A \sqrt{2\varepsilon_s q \left(\frac{N_A N_D}{N_A + N_D}\right) \left(\frac{V_0 + V_R}{action}\right)}_{\substack{\text{action:} \\ \text{replace } V_0 \\ \text{with } V_0 + V_R}}$$

Reverse Biased Diode's Application: Voltage-Dependent Capacitor



The PN junction can be viewed as a capacitor. By varying V_R , the depletion width changes, changing its capacitance value; therefore, the PN junction is actually a voltage-dependent capacitor.

Example 3.5

Consider a *pn* junction in equilibrium at room temperature (T = 300 K) for which the doping concentrations are $N_{4} = 10^{18}$ /cm³ and $N_{D} = 10^{16}$ /cm³ and the cross-sectional area $A = 10^{-4}$ cm². Calculate p_{p} , n_{p0} , n_{n} , p_{n0} , V_{0} , W, x_{n} , x_{p} , and Q_{J} . Use $n_{i} = 1.5 \times 10^{10}$ /cm³.

Solution

$$p_p \simeq N_A = 10^{18} \text{ cm}^{-3}$$

$$n_{p0} = \frac{n_i^2}{p_p} \simeq \frac{n_i^2}{N_A} = \frac{(1.5 \times 10^{10})^2}{10^{18}} = 2.25 \times 10^2 \text{ cm}^{-3}$$

$$n_n \simeq N_D = 10^{16} \text{ cm}^{-3}$$

$$p_{n0} = \frac{n_i^2}{n_n} \simeq \frac{n_i^2}{N_D} = \frac{(1.5 \times 10^{10})^2}{10^{16}} = 2.25 \times 10^4 \text{ cm}^{-3}$$

$$V_O = V_T \ln\left(\frac{N_A N_D}{n_i^2}\right)$$

where

$$V_T = \frac{kT}{q} = \frac{8.62 \times 10^{-5} \times 300 \text{ (eV)}}{q \text{ (e)}}$$

= 25.9 × 10^{-3} V

Thus,

$$V_0 = 25.9 \times 10^{-3} \ln \left(\frac{10^{18} \times 10^{16}}{2.25 \times 10^{20}} \right)$$

= 0.814 V

To determine W we use Eq. (3.26):

$$W = \sqrt{\frac{2 \times 1.04 \times 10^{-12}}{1.6 \times 10^{-19}}} \left(\frac{1}{10^{18}} + \frac{1}{10^{16}}\right) \times 0.814$$

= 3.27 × 10⁻⁵ cm = 0.327 µm

To determine x_n and x_p we use Eq. (3.27) and (3.28), respectively:

$$x_n = W \frac{N_A}{N_A + N_D}$$

= 0.327 $\frac{10^{18}}{10^{18} + 10^{16}}$ = 0.324 µm
$$x_p = W \frac{N_D}{N_A + N_D}$$

= 0.327 $\frac{10^{16}}{10^{18} + 10^{16}}$ = 0.003 µm

Finally, to determine the charge stored on either side of the depletion region, we use Eq. (3.29)

$$Q_{J} = |Q_{\pm}| = Aq \left(\frac{N_{A}N_{D}}{N_{A} + N_{D}}\right) W \qquad \qquad Q_{J} = 10^{-4} \times 1.6 \times 10^{-19} \left(\frac{10^{18} \times 10^{16}}{10^{18} + 10^{16}}\right) \times 0.327 \times 10^{-4}$$
$$= 5.18 \times 10^{-12} \text{ C} = 5.18 \text{ pC}$$



➤ What happens, exactly, when a forward-bias voltage (VF) is applied to the pn-junction? step #1: Initially, a small forward-bias voltage (V_F) is applied. It, because of its polarity, pushes majority (holes in p-region and electrons in *n*-region) toward the junction and reduces width of the depletion zone.



Step #2: As the magnitude of V_F increases, the depletion zone becomes thin enough such that the barrier voltage ($V_0 - V_F$) cannot stop diffusion current − as described in previous slides.



step #3: Majority carriers (free electrons in *n*-region and holes in *p*-region) cross the junction and become minority charge carriers in the near-neutral region.



step #4: The concentration of minority charge carriers increases on either side of the junction. A steady-state gradient is reached as rate of majority carriers crossing the junction equals that of recombination.



step #5: Diffusion current is maintained – in spite low diffusion lengths (e.g. microns) and recombination – by constant flow of both free electrons and holes towards the junction.





For forward-biased case, how is diffusion current (I_D) defined?

$$I = \left(Aqn_i^2 \left[\frac{D_p}{L_pN_D} + \frac{D_n}{L_nN_A}\right]\right) (e^{V/V_T} - 1) = I_s (e^{V/V_T} - 1)$$

saturation current (I_S) – is the maximum reverse current which will flow through *pn*-junction.

- ▶ It is proportional to **cross-section of junction** (*A*).
- ▶ Typical value is 10⁻¹⁸A.



Example 6: *pn*-Junction

- Consider a forward-biased *pn* junction conducting a current of *I* = 0.1*mA* with following parameters:
 - ► $N_A = 10^{18}/cm^3$, $N_D = 10^{16}/cm^3$, $A = 10^{-4}cm^2$, $n_i = 1.5e^{10}/cm^3$, $L_p = 5um$, $L_n = 10um$, D_p (*n*-region) = $10cm^2/s$, D_n (*p*-region) = $18cm^2/s$
- **Q(a):** Calculate I_S .
- Q(b): Calculate the forward bias voltage (V).
- **Q(c):** Component of current *I* due to hole injection and electron injection across the junction.

a)

$$I_{S} = Aqn_{i}^{2} \left(\frac{D_{p}}{L_{p}N_{D}} + \frac{D_{n}}{L_{n}N_{A}} \right)$$

$$I_{S} = 10^{-4} \times 1.6 \times 10^{-19} \times (1.5 \times 10^{10})^{2} \times \left(\frac{10}{5 \times 10^{-4} \times 10^{16}} + \frac{18}{10 \times 10^{-4} \times 10^{18}} \right)$$

$$= 7.3 \times 10^{-15} \text{ A}$$

(b) In the forward direction,

$$I = I_{S}(e^{V/V_{T}} - 1)$$
$$\simeq I_{S}e^{V/V_{T}}$$

Thus,

For I = 0.1 mA,

$$V = V_T \ln\left(\frac{I}{I_S}\right)$$

$$V = 25.9 \times 10^{-3} \ln \left(\frac{0.1 \times 10^{-3}}{7.3 \times 10^{-15}} \right)$$
$$= 0.605 \text{ V}$$

(c) The hole-injection component of I can be found using Eq. (3.37)

$$I_{p} = Aq \frac{D_{p}}{L_{p}} p_{n0}(e^{V/V_{T}} - 1)$$
$$= Aq \frac{D_{p}}{L_{p}} \frac{n_{i}^{2}}{N_{D}}(e^{V/V_{T}} - 1)$$

Similarly I_n can be found using Eq. (3.39),

$$I_n = Aq \frac{D_n}{L_n} \frac{n_i^2}{N_A} (e^{V/V_T} - 1)$$

Thus,

$$\frac{I_p}{I_n} = \left(\frac{D_p}{D_n}\right) \left(\frac{L_n}{L_p}\right) \left(\frac{N_A}{N_D}\right)$$

For our case,

$$\frac{I_p}{I_n} = \frac{10}{18} \times \frac{10}{5} \times \frac{10^{18}}{10^{16}} = 1.11 \times 10^2 = 111$$

Thus most of the current is conducted by holes injected into the n region.

Specifically,

$$I_p = \frac{111}{112} \times 0.1 = 0.0991 \text{ mA}$$

 $I_n = \frac{1}{112} \times 0.1 = 0.0009 \text{ mA}$

This stands to reason, since the p material has a doping concentration 100 times that of the n material.

END OF LECTURE

BEST WISHES